

Model Number: L3

- Desktop Liquid Cooling Solution Recommended for CPU Models As Following,
 - Intel® Processor, Socket LGA2011, Square ILM Mounting
 - Intel® Processor, Socket LGA2011, Narrow ILM Mounting
 - Intel® Processor, Socket LGA1356, 1366
 - Intel® Processor, Socket LGA1150, 1151, 1155, 1156
 - Intel® Processor, Socket LGA1200
 - AMD® Processor, Socket AM2, AM2+, AM3, AM4, FM1, FM2
- For One-U Server and up

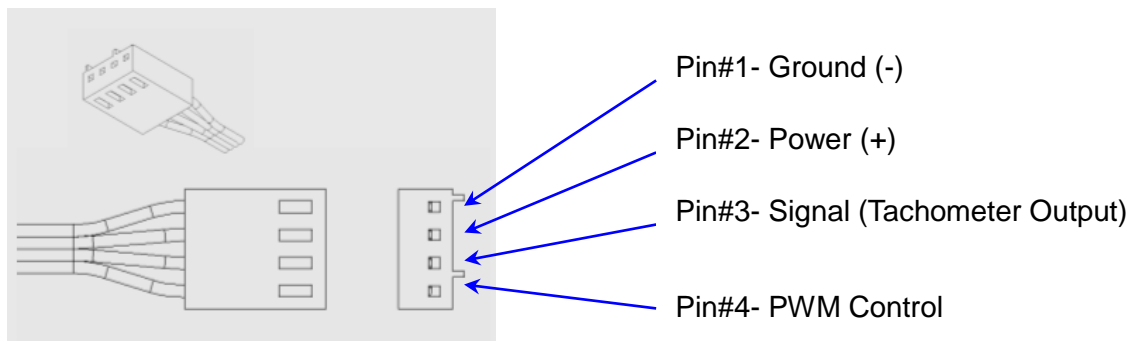
Overall Description :

- Cold Plate Module with Copper Base
- Space Saver Light Weight Radiator
- 4cm Cooling Fans with 4-Pin PWM Connector
- Stand-alone Water Pump with Powerful Flow Rate 1.7 Liter Per Minute
- 30cm Black Pair EPDM Tube Assembled
- Mounting Accessories are included
- Shin-Etsu Series Thermal Compound Pre-Printed on Base
- Support CPU Overclocking Power Mode up to 165Watts Heat Dissipation

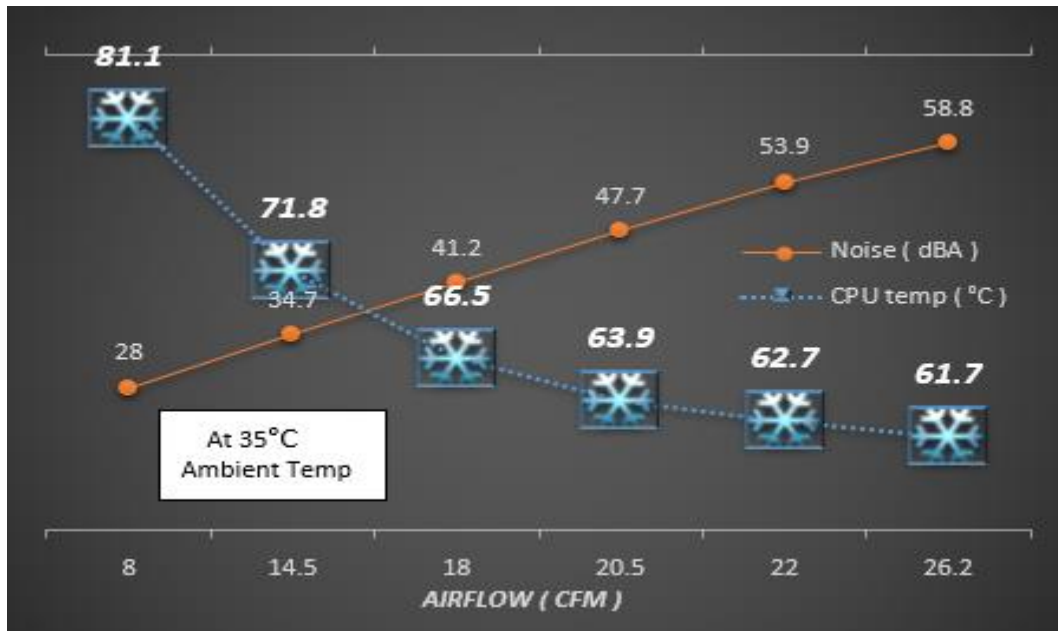
Cooling Fan Specification:

- Model Number: DF124028BM - PWMG
- Dimension: 40mm x 40mm x 28mm
- Bearing Type: Ball, Dual
- Rated Voltage: 12V
- Rated Speed:
 - At Duty Cycle 0~20%: 3300±10% RPM
 - At Duty Cycle 50%: 5700±10% RPM
 - At Duty Cycle 100%: 12000±10% RPM

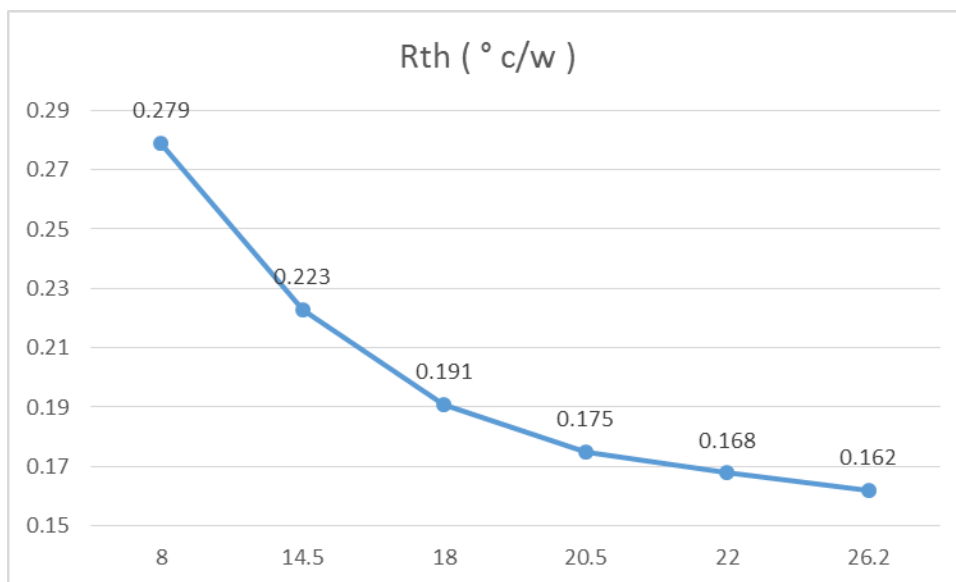
- Rated Input Power:
 - At Duty Cycle 0~20%: 0.72 W
 - At Duty Cycle 50%: 1.56 W
 - At Duty Cycle 100%: 8.40 W
- Rated Airflow:
 - At Duty Cycle 0~20%: 5.92 CFM
 - At Duty Cycle 50%: 10.23 CFM
 - At Duty Cycle 100%: 21.53 CFM
- Rated Static Pressure:
 - At Duty Cycle 0~20%: 1.73 mm-H₂O
 - At Duty Cycle 50%: 5.17 mm-H₂O
 - At Duty Cycle 100%: 22.91 mm-H₂O
- Rated Acoustical Noise:
 - At Duty Cycle 0~20%: 25.9 dBA
 - At Duty Cycle 50%: 37.8 dBA
 - At Duty Cycle 100%: 54.0 dBA
- Lead Wire Pin Out Diagram :



Liquid Cooler L3 Thermal Performance (Airflow VS. CPU Temperature & Noise)

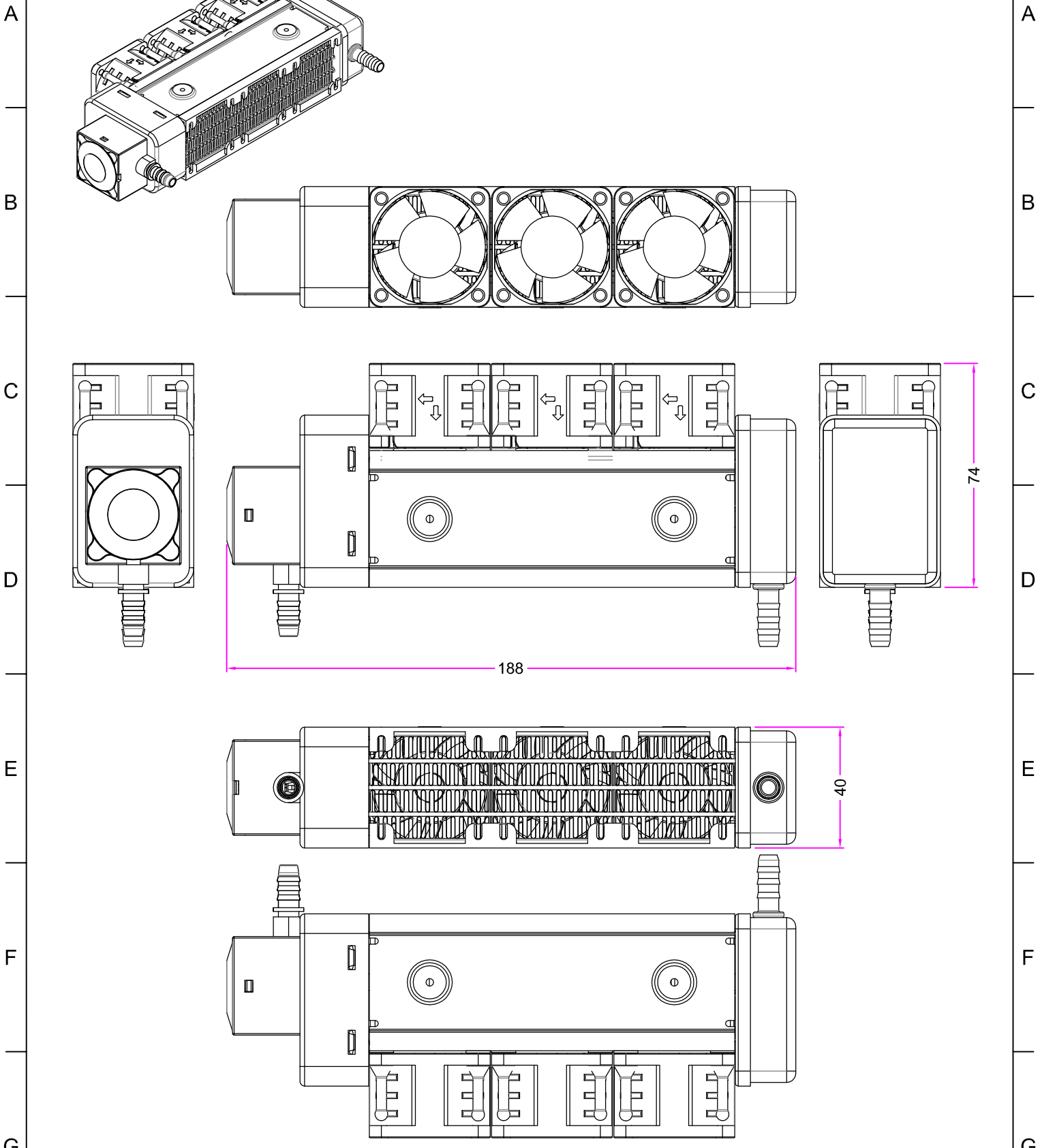


(Airflow VS. Thermal Resistance)



1 2 3 4 5 6 7

REV#	DESCRIPTION	CHECKER	DATE
0.0	INITIAL RELEASE	LANG	03/31/2015



	NAME	DATE
DRAWN BY	ENGR	03/31/15
CHECKED BY	LANG	03/31/15
ENG. APPROVED		
MFG. APPROVED	-	-



DYNATRON CORPORATION

TOP MOTOR

TITLE: 1U Server Liquid Cooler Condenser L3
Overall Dimension Drawing

CONFIDENTIAL DOCUMENT
THIS DRAWING CONTAINS INFORMATION PROPRIETARY TO DYNATRON CORPORATION AND DYNAEON INDUSTRIAL CO., LTD. ANY REPRODUCTION, DISCLOSURE, OR USE OF THIS DRAWING IS EXPRESSLY PROHIBITED EXCEPT AS DYNATRON CORPORATION AND DYNAEON INDUSTRIAL CO., LTD. MAY OTHERWISE AGREE TO IN WRITING.

VIEW	
UNITS	MM

DWG. No:	
REV.	0.0

1 2 3 4 5 6 7

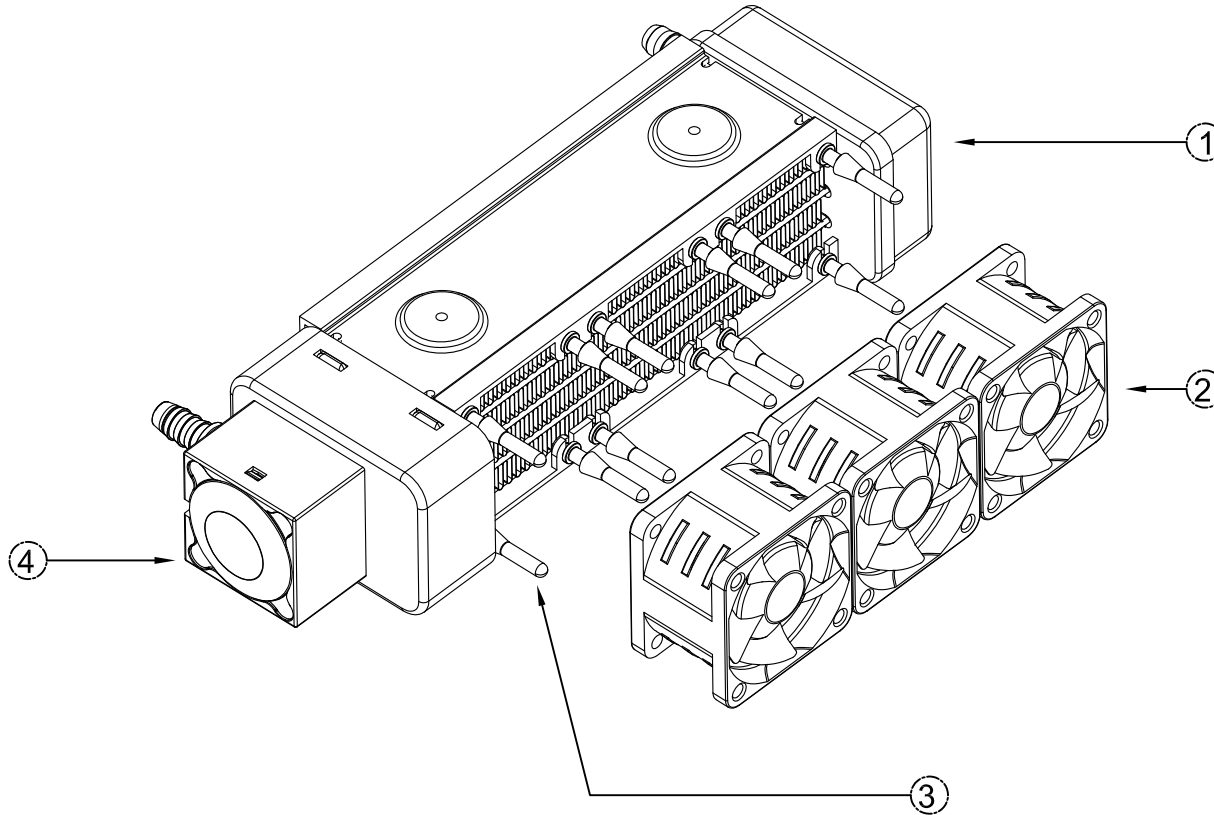
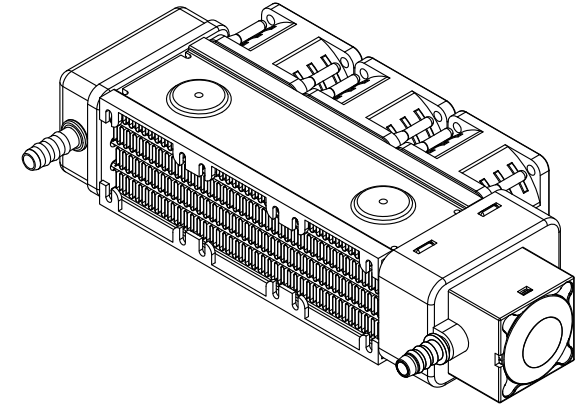
CONFIDENTIAL DOCUMENT

THIS DRAWING CONTAINS INFORMATION PROPRIETARY TO DYNATRON CORPORATION AND DYNAEON INDUSTRIAL CO., LTD. ANY REPRODUCTION, DISCLOSURE, OR USE OF THIS DRAWING IS EXPRESSLY PROHIBITED EXCEPT AS DYNATRON CORPORATION AND DYNAEON INDUSTRIAL CO., LTD. MAY OTHERWISE AGREE TO IN WRITING.

REV#	DESCRIPTION	CHECKER	DATE
0.0	INITIAL RELEASE	LANG	10/08/2015

ASSEMBLY PARTS


WHOLE SET OF CONDENSER



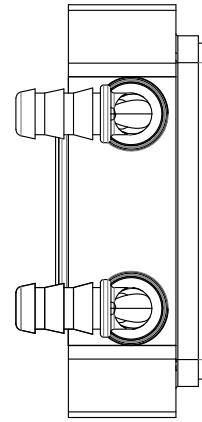
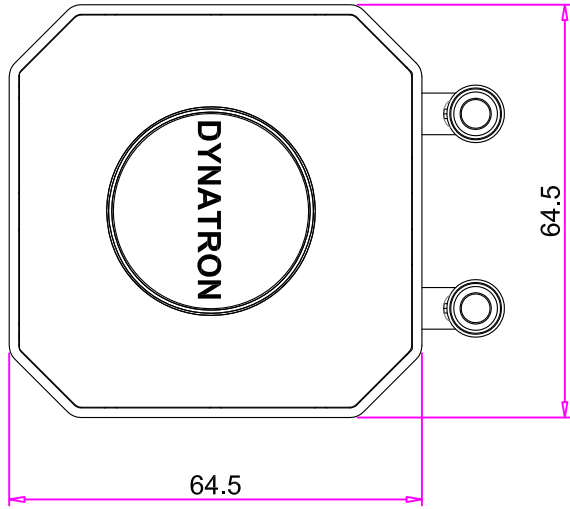
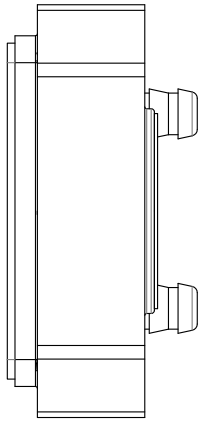
4	Pump Enclosure	Plastic	1
3	Grommet	Rubber	12
2	Fan, DF124028BM-PWM, 12000RPM	Plastic	3
1	Radiator	Aluminum Alloy	1
ITEM#	DESCRIPTION	MATERIAL	QTY.

Notes:

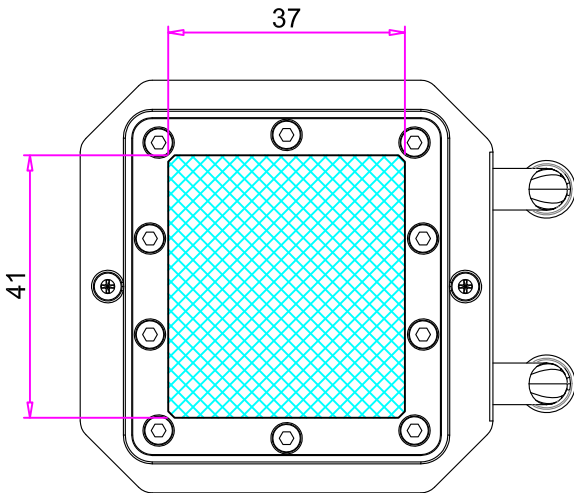
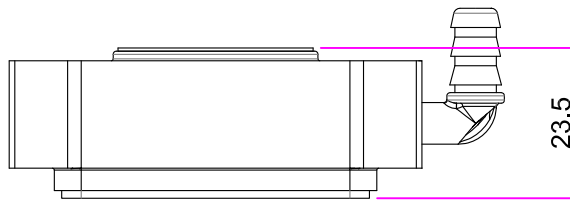
1. The Figure is For Reference Only, and Not For Scale
2. Overall Dimension: 188 x 74 x 40 mm

DATE	NAME	 DYNATRON CORPORATION
DRAWN	ENGR	
CHECKED	LANG	
ENG. APPR.		
MFG. APPR.		
Q.A.		TITLE: 1U Liquid Cooler L3 Condenser BOM & Exploded Assembly Drawing
COMMENTS:		
DWG. No:		REV
DYN-EP-L3		0.0

REV#	DESCRIPTION	CHECKER	DATE
0.0	INITIAL RELEASE	LANG	10/07/15
1.0	ADD THERMAL GREASE PRE-APPLIED, F-3	LANG	12/04/15



0.10
Ra < 1.2
Grind



8	Thermal Grease, Pre-applied	Shin-Etsu 7762	1
7	Retaining Ring	Rubber	1
6	O-ring	Rubber	6
5	Nipple, 90° Angle	Plastic	2
4	Cold Plate Screw	Steel	10
3	Cold Plate Lid Screw	Steel	2
2	Cold Plate Lid	Plastic	1
1	Cold Plate Set	Enclosure Base	Plastic
		Base	Copper 1100
ITEM#	DESCRIPTION	MATERIAL	QTY.

	NAME	DATE
DRAWN BY	ENGR	12/04/2015
CHECKED BY	LANG	12/04/2015
ENG.APPROVED		
MFG.APPROVED	-	-



DYNATRON CORPORATION

TITLE: Liquid Cooler Cold Plate
BOM & Overall Dimension Drawing

CONFIDENTIAL DOCUMENT

THIS DRAWING CONTAINS INFORMATION PROPRIETARY TO DYNATRON CORPORATION AND DYNAEON INDUSTRIAL CO., LTD. ANY REPRODUCTION, DISCLOSURE, OR USE OF THIS DRAWING IS EXPRESSLY PROHIBITED EXCEPT AS DYNATRON CORPORATION AND DYNAEON INDUSTRIAL CO., LTD. MAY OTHERWISE AGREE TO IN WRITING.

VIEW	
UNITS	MM

DWG. No: **DYN-BD-LCP**

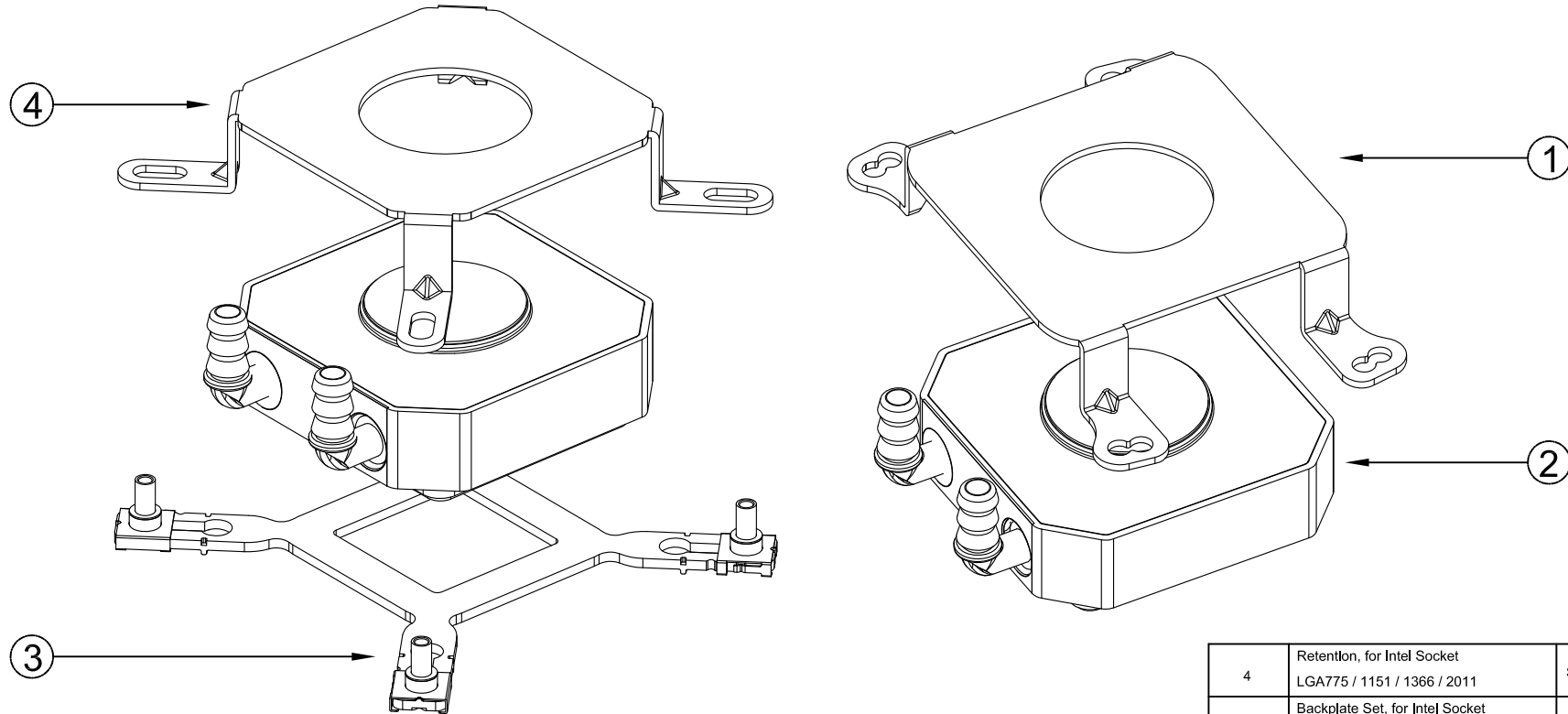
REV. **1.0**

CONFIDENTIAL DOCUMENT


THIS DRAWING CONTAINS INFORMATION PROPRIETARY TO DYNATRON CORPORATION AND DYNAEON INDUSTRIAL CO., LTD. ANY REPRODUCTION, DISCLOSURE, OR USE OF THIS DRAWING IS EXPRESSLY PROHIBITED EXCEPT AS DYNATRON CORPORATION AND DYNAEON INDUSTRIAL CO., LTD. MAY OTHERWISE AGREE TO IN WRITING.

REV#	DESCRIPTION	CHECKER	DATE
0.0	Initial Release	LANG	10/07/15

ASSEMBLY PARTS



4	Retention, for Intel Socket LGA775 / 1151 / 1366 / 2011	SPCC	1
3	Backplate Set, for Intel Socket LGA775 / 1151 / 1366 / 2011	Steel	1
2	Cold Plate Set	Enclosure	Plastic
		Base	Copper 1100
1	Retention for Intel Socket2011 Narrow for AMD Socket AM3 / AM2 / FM1 / FM2	SPCC	1
ITEM NO.	DESCRIPTION	MATERIAL	QTY.

DATE	NAME	 DYNATRON CORPORATION	
DRAWN	10/07/15 ENGR		TITLE:
CHECKED	10/07/15 LANG		Liquid Cooler Cold Plate BOM & Exploded Drawing
ENG. APPR.			
MFG. APPR.			
Q.A.			
COMMENTS:		DWG. No:	REV
		DYN-EP-LCP	0.0